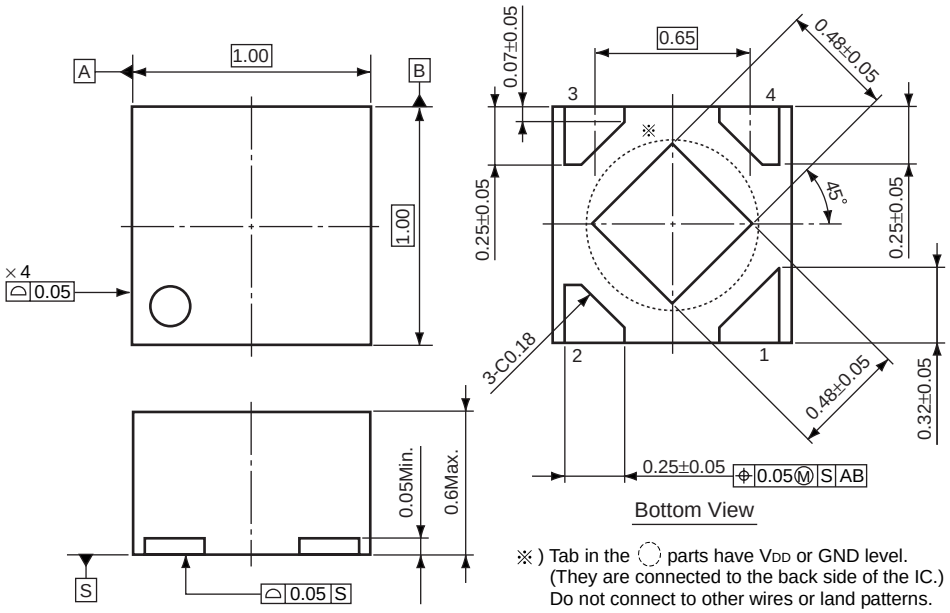
- **DFN(PLP)1010-4**

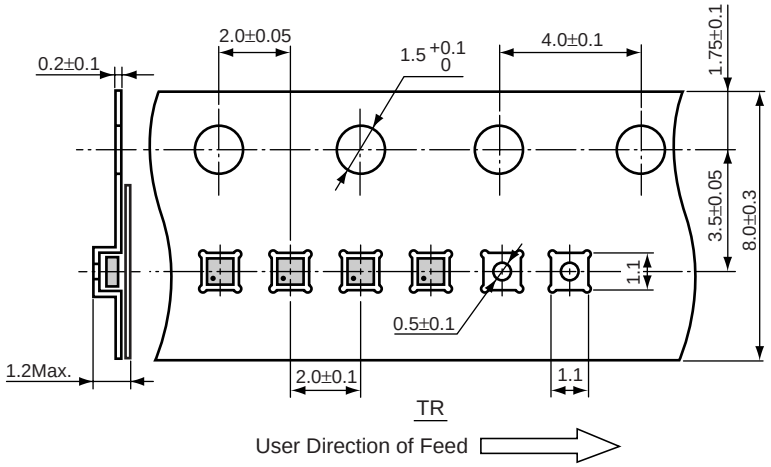
Unit: mm

PACKAGE DIMENSIONS



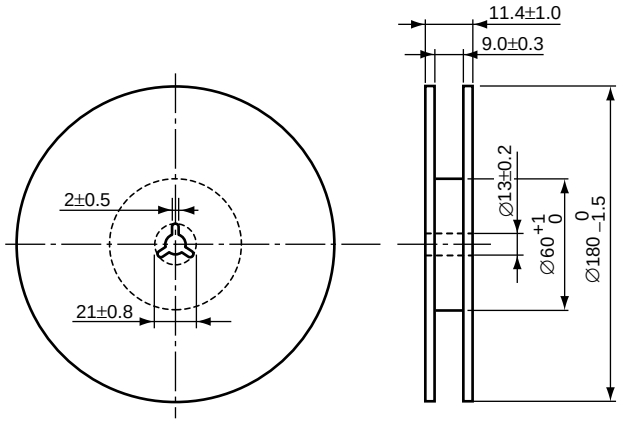
※) Tab in the ◌ parts have V_{DD} or GND level.
(They are connected to the back side of the IC.)
Do not connect to other wires or land patterns.

TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1reel=10,000pcs)



POWER DISSIPATION (DFN(PLP)1010-4)

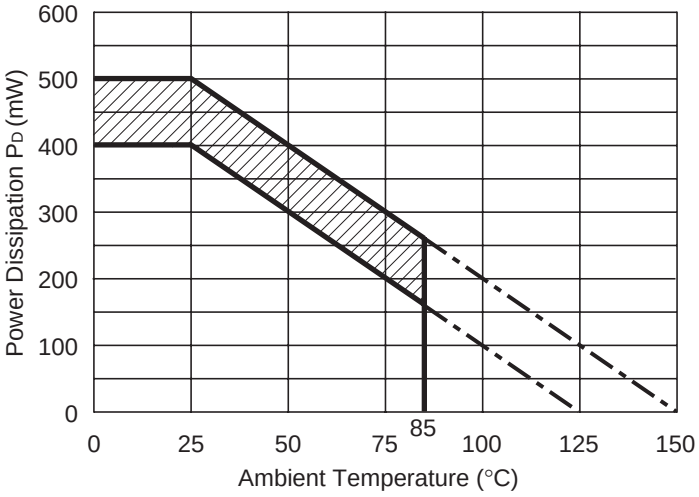
This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

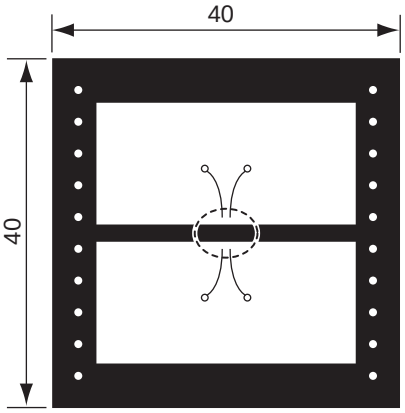
	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-holes	ϕ0.54mm × 24pcs

Measurement Results (Topt=25°C, Tjmax=125°C)

	Standard Land Pattern
Power Dissipation	400mW
Thermal Resistance	θja=(125−25°C)/0.4W=250°C/W
Thermal Resistance	θjc=67°C/W



Power Dissipation



Measurement Board Pattern

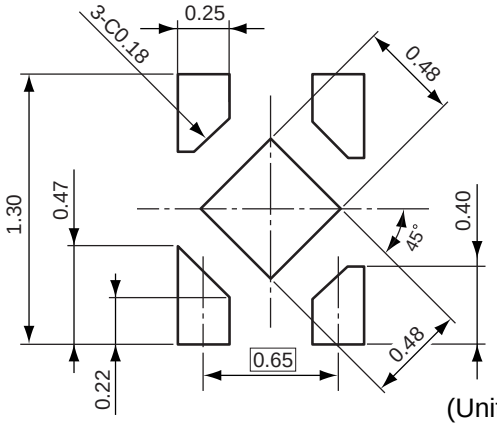
IC Mount Area (Unit: mm)

The above graph shows the Power Dissipation of the package based on Tjmax=125°C and Tjmax=150°C.
Operating the IC in the shaded area in the graph might have an influence it's lifetime.
Operating time must be within the time limit described in the table below, in case of operating in the shaded area.

Product Name	Operating time	Estimated years*
RP103K RP104K RP130K RP114K	13,000hrs	9years

*The volume is calculated on the supposition that operating four hours/day.

RECOMMENDED LAND PATTERN



(Unit: mm)